IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method of manufacturing a liquid crystal display device, comprising:

preparing glass substrates used for said liquid crystal display device;

preparing first and second etching process machines containing first and second etching solutions, respectively, said first etching solution being faster in etching rate than said second etching solution, said first etching solution removing small defects or micro-cracks on surfaces of said substrates from the surfaces of said glass substrates and said second etching solution making said glass substrate as thin as desirable; and

etching surfaces of said glass substrates in the first and second etching process machines by using said first etching solution and then said second etching solution, respectively,

wherein a ratio of said etching rate of said first etching solution to that of said second etching solution is 100:1 or more.

Claim 2 (Original): The method of manufacturing a liquid crystal display device according to claim 1, wherein said glass substrates include electrode patterns formed on said surfaces thereof and are put together, and said etching step is carried out for at least one surface of said glass substrates.

Claim 3 (Canceled).

Claim 4 (Withdrawn): Equipment for manufacturing a liquid crystal display device, comprising:

a carrier to take and transfer glass substrates used for said liquid crystal display device;

first and second etching solutions, said first etching solution being faster in etching rate than said second etching solution said first etching solution removing small defects or micro-cracks from a surface of said glass substrates and said second etching solution flattening said surface of said glass substrates; and

an etching process machine to etch surfaces of said glass substrates by using said first etching solution and then said second etching solution.

Claim 5 (Currently Amended): The method of manufacturing a liquid crystal display device according to claim 1,

wherein ~~said first etching solution is used at a normal temperature but said second etching solution is used at a higher temperature than the normal temperature~~ a temperature of said first etching solution is higher than that of said second etching solution.